

AMENDMENTS TO THE CLAIMS

Claims 1-5 (Canceled)

Claim 6 (Currently Amended) An integrated circuit arrangement comprising a nonplanar substrate in which an integrated circuit is formed on a ~~side of the~~ substrate arranged on a carrier and on a same side of the substrate facing the carrier, wherein the carrier is produced from a chemically resistant material.

Claim 7 (Previously Presented) The integrated circuit arrangement as claimed in claim 6, wherein the chemically resistant material of the carrier is formed from ceramic.

Claim 8 (Previously Presented) The integrated circuit arrangement as claimed in claim 7, wherein a side of the carrier which is remote from the integrated circuit has a planar surface.

Claim 9 (Previously Presented) The integrated circuit arrangement as claimed in claim 8, wherein the entire area of the at least one side of the substrate is connected to the carrier.

Claim 10 (Previously Presented) The integrated circuit arrangement as claimed in claim 9, wherein the carrier has a cavity in which the substrate is completely held.

Claim 11 (Previously Presented) The integrated circuit arrangement as claimed in claim 8, wherein the carrier has a cavity in which the substrate is completely held.

Claim 12 (Previously Presented) The integrated circuit arrangement as claimed in claim 7, wherein the entire area of the at least one side of the substrate is connected to the carrier.

Claim 13 (Previously Presented) The integrated circuit arrangement as claimed in claim 12, wherein the carrier has a cavity in which the substrate is completely held.

Claim 14 (Previously Presented) The integrated circuit arrangement as claimed in claim 7, wherein the carrier has a cavity in which the substrate is completely held.

Claim 15 (Previously Presented) The integrated circuit arrangement as claimed in claim 6, wherein a side of the carrier which is remote from the integrated circuit has a planar surface.

Claim 16 (Previously Presented) The integrated circuit arrangement as claimed in claim 15, wherein the entire area of the at least one side of the substrate is connected to the carrier.

Claim 17 (Previously Presented) The integrated circuit arrangement as claimed in claim 16, wherein the carrier has a cavity in which the substrate is completely held.

Claim 18 (Previously Presented) The integrated circuit arrangement as claimed in claim 15, wherein the carrier has a cavity in which the substrate is completely held.

Claim 19 (Previously Presented) The integrated circuit arrangement as claimed in claim 6, wherein the entire area of the at least one side of the substrate is connected to the carrier.

Claim 20 (Previously Presented) The integrated circuit arrangement as claimed in claim 19, wherein the carrier has a cavity in which the substrate is completely held.

Claim 21 (Previously Presented) The integrated circuit arrangement as claimed in claim 6, wherein the carrier has a cavity in which the substrate is completely held.

Claim 22 (Currently Amended) An integrated circuit arrangement comprising a curved substrate having an integrated circuit formed in ~~the outer side of the~~ substrate arranged on a carrier and on a same side of the substrate facing the carrier, wherein the carrier is produced from a chemically resistant material.

Claim 23 (Previously Presented) The integrated circuit arrangement as claimed in claim 22, wherein the chemically resistant material of the carrier is formed from ceramic.

Claim 24 (Previously Presented) The integrated circuit arrangement as claimed in claim 22, wherein a side of the carrier which is remote from the integrated circuit has a planar surface.

Claim 25 (Previously Presented) The integrated circuit arrangement as claimed in claim 22, wherein the entire area of the outer side of the curved substrate is connected to the carrier.

Claim 26 (Previously Presented) The integrated circuit arrangement as claimed in claim 22, wherein the carrier has a cavity in which the curved substrate is completely held.